

## Substrate Spinner EBS 8x

The newly designed, versatile **Reinraumtechnik Lanz** spinner module with high torque 3-phase AC-motor and PWM servo controller.

Depending upon the option selected, the spinner can be used for coating, developing or cleaning wafers and substrates. The optional built-in dispense arm allows for automated processing of single substrates.

### Description

User-friendly operation via touch panel. The program holds 30 recipes with 30 user-determined process cycles.

One process cycle consists of the following parameters:

Time:	0-999.9s
Speed:	0-6000 / min.
Acceleration:	0-25.000 rpm/sec. substrate depending
Output selection:	6 (basic system)

A variety of auto dispense options and customized chucks are available upon request.

Especially designed for laboratory and other low volume use, the EBS 8x can be flush-mounted or ordered as a stand-alone model.



EBS-8x shown as in-deck model



Touch Panel EBS 8x

### Features and Benefits

- For substrates up to 8" square
- For wafers up to 300mm Ø
- Easy to use and program
- Cover interlock (prevents the user from opening the cover during operation)
- Vacuum interlock
- Touch Panel
- CE marking
- 12 months warranty

For more details, please contact Reinraumtechnik Lanz – Germany at [info@rrt-lanz.com](mailto:info@rrt-lanz.com)  
Subject to change without prior notice.

## Facility Requirements

- Voltage/Power: 110V/230V / 50-60 Hz
- Vacuum: -0.8 bar, 5 l /min 4mm Ø connection
- Air Pressure: 4 bar, 0.5 l /min 4mm Ø
- Exhaust: -0.1 bar, 100 l /min 32mm Ø

## Dimensions

- Baseplate: w x d = 400mm x 500mm (aluminium) for in-deck mounting
- Height: 560mm (with exhaust and drain bottle 1.5 l)  
300mm (without drain bottle)
- Bowl: 340mm Ø (POM), depth = 90mm

## Options

- Manual centering tool for up to 150mm wafers (recommended for non-centering chucks)
- Splash rings for up to 150mm wafers
- Chucks for special substrates and sizes
- EBR (edge-bead-removal) / BSR (back-side-rinse)
- Special materials (i.e. PVDF) for bowl and cover
- Stand-alone enclosure (w x d x h = 450mm x 550mm x 790mm)
- Pneumatic dispense arm (left-hand side at bowl)
- Pneumatic second dispense arm (right-hand side at bowl)
- Programmable dispense arm for up to 4 nozzles
- Dispense pump
- Dispense systems

### Option: Coater

- Dispensing pump
- BSR EBR

### Option: Developer

- Dispensing pump
- Fluid valves for DI water, developer, N<sub>2</sub>
- Media tanks

### Option: Cleaner

- High Pressure Arm with pump in separate enclosure (8800 PSI)
- Megasonic nozzle
- Fluid valves for solvents
- Media tanks